



Final Product/Process Change Notification

Document #:FPCN25572Z27

Issue Date:28 Mar 2024

Title of Change:	Update to FPCN25572Z - To include the reliability data for QFN-16 package parts for the Qualification of Vanguard Fab and Assembly related changes for Logic parts.
Proposed Changed Material First Ship Date:	05 Oct 2024 or earlier if approved by customer
Current Material Last Order Date:	20 Nov 2023 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local onsemi Sales Office or logic.fpcn@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	31 Mar 2024
PPAP Availability Date:	10 Apr 2024
Additional Reliability Data:	Contact your local onsemi Sales Office or ChangKit.Mok@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .
Change Category	
Category	Type of Change
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor
Equipment	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product
Data Sheet	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Change of mold compound, Die attach material, Change of lead frame finishing material / area (internal), Change of wire bonding, Change of lead and heat slug plating material/plating thickness (external)

Description and Purpose:

With reference to **FPCN25572Z**, this FPCN presents the information solely for QFN-16 and the pertinent reliability data.

	From	To
Fab Site	Tower Semiconductor	Vanguard International Semiconductor (VIS)
Wafer Size	150 mm	200 mm

Assembly and test changes as shown in the table below:

	From	To
Assembly Site	onsemi Seremban	onsemi Tarlac
Test Site	onsemi Seremban	onsemi Tarlac
Leadframe	Selective Ag Plated	PPF
Die Attach	DA AB 8006NS	CRM-1076WB
Bond Wire	0.8 mil AU	0.8 mil PCC
Mold Compound	EME-G760	EME-G770HM Type D

There is no product marking change as a result of this change

Reason / Motivation for Change:	Supply disruption
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.
Sites Affected:	
onsemi Sites	External Foundry/Subcon Sites
onsemi Tarlac, Philippines	Vanguard International Semiconductor, Taiwan
Marking of Parts/ Traceability of Change:	Custom source on label will show TW instead of US/JP to indicate new die source from Vanguard. Changed material may be identified by plant code or lot code too.

Reliability Data Summary:

QV DEVICE NAME : NLV74HC595AMN1TWG

RMS : S89269 / S92696

PACKAGE : QFN-16

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs	0/2400
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only	-	0/693
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

QV DEVICE NAME : NLV74HC4851AMN1TWG

RMS : S90474

PACKAGE : QFN-16

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/77
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/77
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only	-	0/231
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/77
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/77
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/77

NOTE: AEC-1pager is attached.

To view attachments:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file.

Electrical Characteristics Summary:

	From	To
Datasheet	Current Revision	New Revision
Absolute Max Voltage Rating	7 V	6.5 V

Additional change for NLV74HC595AMN1TWG

Existing Datasheet

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{IN}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
I _{IN}	DC Input Current, per Pin	±20	mA
I _{OUT}	DC Output Current, per Pin	±35	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±75	mA
P _D	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T _{stg}	Storage Temperature	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC or TSSOP Package)	260	°C
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	> 3000 > 400 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

†Derating: SOIC Package: -7 mW/°C from 65° to 125° C
TSSOP Package: -6.1 mW/°C from 65° to 125° C

1. Tested to EIA/JESD22-A114-A
2. Tested to EIA/JESD22-A115-A
3. Tested to JESD22-C101-A

New

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +6.5	V
V _{IN}	DC Input Voltage	-0.5 to V _{CC} + 0.5	V
V _{OUT}	DC Output Voltage	-0.5 to V _{CC} + 0.5	V
I _{IN}	DC Input Current, per Pin	±20	mA
I _{OUT}	DC Output Current, per Pin	±35	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±75	mA
I _{IK}	Input Clamp Current (V _{IN} < 0 or V _{IN} > V _{CC})	±20	mA
I _{OK}	Output Clamp Current (V _{OUT} < 0 or V _{OUT} > V _{CC})	±20	mA
T _{STG}	Storage Temperature	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction Temperature Under Bias	150	°C
θ _{JA}	Thermal Resistance (Note 1)	SOIC-16: 126 QFN16: 118 TSSOP-16: 159	°C/W
P _D	Power Dissipation in Still Air at 25°C	SOIC-16: 995 QFN16: 1062 TSSOP-16: 787	mW
MSL	Moisture Sensitivity	Level 1	-
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
V _{ESD}	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model	>3000 N/A

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 76mm-by-114mm, 2-ounce copper trace no air flow per JESD51-7.
2. HBM tested to EIA/JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NLV74HC4851AMN1TWG	MC74HC4851AMN1TWG-Q	NLV74HC4851AMN1TWG
NLV74HC595AMN1TWG	MC74HC595AMN1TWG-Q	NLV74HC595AMN1TWG